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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	CANbus, EBI/EMI, I²C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	2MB (2M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	384K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 16x12b SAR; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32gg11b110f2048iq64-br

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4. Electrical Specifications

4.1 Electrical Characteristics

All electrical parameters in all tables are specified under the following conditions, unless stated otherwise:

- Typical values are based on $T_{AMB}=25\text{ }^{\circ}\text{C}$ and $V_{DD}=3.3\text{ V}$, by production test and/or technology characterization.
- Minimum and maximum values represent the worst conditions across supply voltage, process variation, and operating temperature, unless stated otherwise.

Refer to [4.1.2.1 General Operating Conditions](#) for more details about operational supply and temperature limits.

4.1.2.1 General Operating Conditions

Table 4.2. General Operating Conditions

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Operating ambient temperature range ⁶	T _A	-G temperature grade	-40	25	85	°C
		-I temperature grade	-40	25	125	°C
AVDD supply voltage ²	V _{AVDD}		1.8	3.3	3.8	V
VREGVDD operating supply voltage ^{2 1}	V _{VREGVDD}	DCDC in regulation	2.4	3.3	3.8	V
		DCDC in bypass, 50mA load	1.8	3.3	3.8	V
		DCDC not in use. DVDD externally shorted to VREGVDD	1.8	3.3	3.8	V
VREGVDD current	I _{VREGVDD}	DCDC in bypass, T ≤ 85 °C	—	—	200	mA
		DCDC in bypass, T > 85 °C	—	—	100	mA
DVDD operating supply voltage	V _{DVDD}		1.62	—	V _{VREGVDD}	V
IOVDD operating supply voltage	V _{IOVDD}	All IOVDD pins ⁵	1.62	—	V _{VREGVDD}	V
DECOUPLE output capacitor ^{3 4}	C _{DECOUPLE}		0.75	1.0	2.75	μF
HFCORECLK frequency	f _{CORE}	VSCALE2, MODE = WS3	—	—	72	MHz
		VSCALE2, MODE = WS2	—	—	54	MHz
		VSCALE2, MODE = WS1	—	—	36	MHz
		VSCALE2, MODE = WS0	—	—	18	MHz
		VSCALE0, MODE = WS2	—	—	20	MHz
		VSCALE0, MODE = WS1	—	—	14	MHz
		VSCALE0, MODE = WS0	—	—	7	MHz
HFCLK frequency	f _{HFCLK}	VSCALE2	—	—	72	MHz
		VSCALE0	—	—	20	MHz
HFSRCCLK frequency	f _{HFSRCCLK}	VSCALE2	—	—	72	MHz
		VSCALE0	—	—	20	MHz
HFBUSCLK frequency	f _{HFBUSCLK}	VSCALE2	—	—	50	MHz
		VSCALE0	—	—	20	MHz
HFPERCLK frequency	f _{HFPERCLK}	VSCALE2	—	—	50	MHz
		VSCALE0	—	—	20	MHz
HFPERBCLK frequency	f _{HFPERBCLK}	VSCALE2	—	—	72	MHz
		VSCALE0	—	—	20	MHz
HFPERCCLK frequency	f _{HFPERCCLK}	VSCALE2	—	—	50	MHz
		VSCALE0	—	—	20	MHz

4.1.9 Brown Out Detector (BOD)

Table 4.11. Brown Out Detector (BOD)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
DVDD BOD threshold	V_{DVDBOD}	DVDD rising	—	—	1.62	V
		DVDD falling (EM0/EM1)	1.35	—	—	V
		DVDD falling (EM2/EM3)	TBD	—	—	V
DVDD BOD hysteresis	V_{DVDBOD_HYST}		—	18	—	mV
DVDD BOD response time	t_{DVDBOD_DELAY}	Supply drops at 0.1V/ μ s rate	—	2.4	—	μ s
AVDD BOD threshold	V_{AVDBOD}	AVDD rising	—	—	1.8	V
		AVDD falling (EM0/EM1)	1.62	—	—	V
		AVDD falling (EM2/EM3)	TBD	—	—	V
AVDD BOD hysteresis	V_{AVDBOD_HYST}		—	20	—	mV
AVDD BOD response time	t_{AVDBOD_DELAY}	Supply drops at 0.1V/ μ s rate	—	2.4	—	μ s
EM4 BOD threshold	$V_{EM4DBOD}$	AVDD rising	—	—	1.7	V
		AVDD falling	1.45	—	—	V
EM4 BOD hysteresis	V_{EM4BOD_HYST}		—	25	—	mV
EM4 BOD response time	t_{EM4BOD_DELAY}	Supply drops at 0.1V/ μ s rate	—	300	—	μ s

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Frequency limits	f_{HFRCO_BAND}	FREQRANGE = 0, FINETUNIN-GEN = 0	1	—	10	MHz
		FREQRANGE = 3, FINETUNIN-GEN = 0	2	—	17	MHz
		FREQRANGE = 6, FINETUNIN-GEN = 0	4	—	30	MHz
		FREQRANGE = 7, FINETUNIN-GEN = 0	5	—	34	MHz
		FREQRANGE = 8, FINETUNIN-GEN = 0	7	—	42	MHz
		FREQRANGE = 10, FINETUNIN-GEN = 0	12	—	58	MHz
		FREQRANGE = 11, FINETUNIN-GEN = 0	15	—	68	MHz
		FREQRANGE = 12, FINETUNIN-GEN = 0	18	—	83	MHz
		FREQRANGE = 13, FINETUNIN-GEN = 0	24	—	100	MHz
		FREQRANGE = 14, FINETUNIN-GEN = 0	28	—	119	MHz
		FREQRANGE = 15, FINETUNIN-GEN = 0	33	—	138	MHz
		FREQRANGE = 16, FINETUNIN-GEN = 0	43	—	163	MHz

Note:

1. Maximum DPLL lock time $\approx 6 \times (M+1) \times t_{REF}$, where t_{REF} is the reference clock period.

4.1.18 Capacitive Sense (CSEN)

Table 4.26. Capacitive Sense (CSEN)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Single conversion time (1x accumulation)	t _{CNV}	12-bit SAR Conversions	—	20.2	—	μs
		16-bit SAR Conversions	—	26.4	—	μs
		Delta Modulation Conversion (single comparison)	—	1.55	—	μs
Maximum external capacitive load	C _{EXTMAX}	CS0CG=7 (Gain = 1x), including routing parasitics	—	68	—	pF
		CS0CG=0 (Gain = 10x), including routing parasitics	—	680	—	pF
Maximum external series impedance	R _{EXTMAX}		—	1	—	kΩ
Supply current, EM2 bonded conversions, WARMUP-MODE=NORMAL, WAR-MUPCNT=0	I _{CSEN_BOND}	12-bit SAR conversions, 20 ms conversion rate, CS0CG=7 (Gain = 1x), 10 channels bonded (total capacitance of 330 pF) ¹	—	326	—	nA
		Delta Modulation conversions, 20 ms conversion rate, CS0CG=7 (Gain = 1x), 10 channels bonded (total capacitance of 330 pF) ¹	—	226	—	nA
		12-bit SAR conversions, 200 ms conversion rate, CS0CG=7 (Gain = 1x), 10 channels bonded (total capacitance of 330 pF) ¹	—	33	—	nA
		Delta Modulation conversions, 200 ms conversion rate, CS0CG=7 (Gain = 1x), 10 channels bonded (total capacitance of 330 pF) ¹	—	25	—	nA
Supply current, EM2 scan conversions, WARMUP-MODE=NORMAL, WAR-MUPCNT=0	I _{CSEN_EM2}	12-bit SAR conversions, 20 ms scan rate, CS0CG=0 (Gain = 10x), 8 samples per scan ¹	—	690	—	nA
		Delta Modulation conversions, 20 ms scan rate, 8 comparisons per sample (DMCR = 1, DMR = 2), CS0CG=0 (Gain = 10x), 8 samples per scan ¹	—	515	—	nA
		12-bit SAR conversions, 200 ms scan rate, CS0CG=0 (Gain = 10x), 8 samples per scan ¹	—	79	—	nA
		Delta Modulation conversions, 200 ms scan rate, 8 comparisons per sample (DMCR = 1, DMR = 2), CS0CG=0 (Gain = 10x), 8 samples per scan ¹	—	57	—	nA

4.1.21 Pulse Counter (PCNT)**Table 4.29. Pulse Counter (PCNT)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input frequency	F_{IN}	Asynchronous Single and Quadrature Modes	—	—	20	MHz
		Sampled Modes with Debounce filter set to 0.	—	—	8	kHz

4.1.22 Analog Port (APORT)**Table 4.30. Analog Port (APORT)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supply current ^{2 1}	I_{APORT}	Operation in EM0/EM1	—	7	—	μA
		Operation in EM2/EM3	—	915	—	nA

Note:

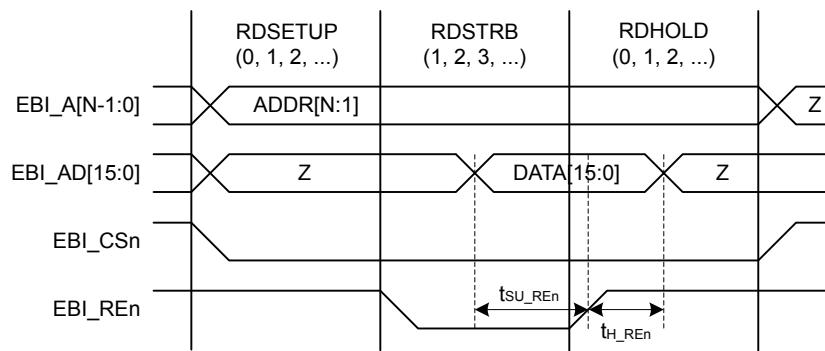
1. Specified current is for continuous APORt operation. In applications where the APORt is not requested continuously (e.g. periodic ACMP requests from LESENSE in EM2), the average current requirements can be estimated by multiplying the duty cycle of the requests by the specified continuous current number.
2. Supply current increase that occurs when an analog peripheral requests access to APORt. This current is not included in reported module currents. Additional peripherals requesting access to APORt do not incur further current.

EBI Read Enable Timing Requirements

Timing applies to both EBI_REn and EBI_NANDREn for all addressing modes and both polarities. All numbers are based on route locations 0,1,2 only (with all EBI alternate functions using the same location at the same time). Timing is specified at 10% and 90% of IOVDD, 25 pF external loading, and slew rate for all GPIO set to 6.

Table 4.40. EBI Read Enable Timing Requirements

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Setup time, from EBI_AD valid to trailing EBI_REn edge	t_{SU_REn}	IOVDD $\geq 1.62\text{ V}$	55	—	—	ns
		IOVDD $\geq 3.0\text{ V}$	36	—	—	ns
Hold time, from trailing EBI_REn edge to EBI_AD invalid	t_{H_REn}	IOVDD $\geq 1.62\text{ V}$	-9	—	—	ns

**Figure 4.7. EBI Read Enable Timing Requirements**

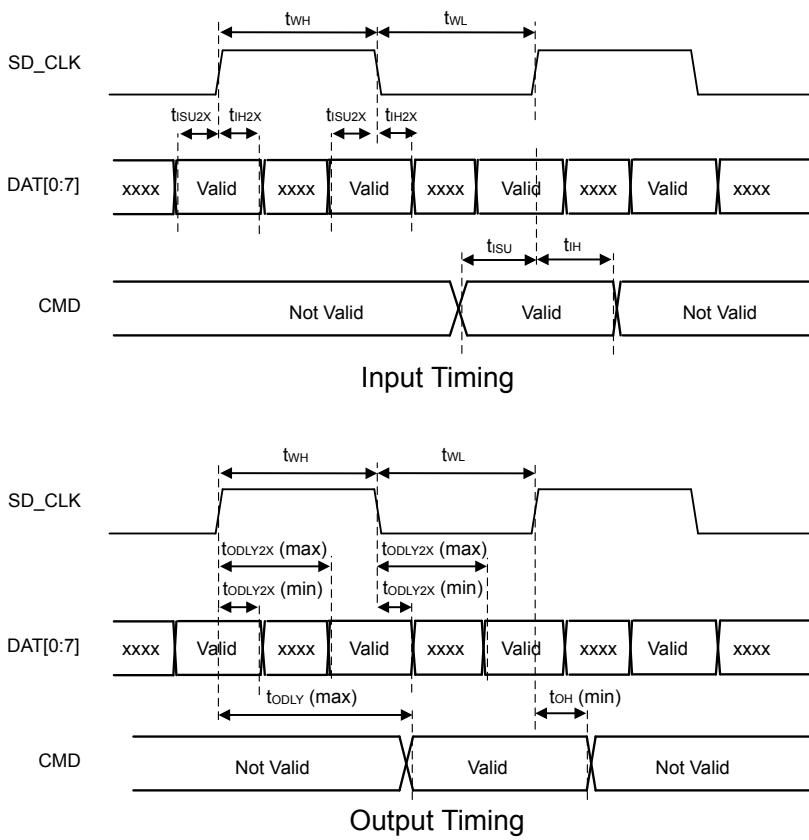


Figure 4.20. SDIO MMC DDR Mode Timing

4.1.28 Quad SPI (QSPI)

4.1.28.1 QSPI SDR Mode

QSPI SDR Mode Timing (Location 0)

Timing is specified with voltage scaling disabled, PHY-mode, route location 0 only, TX DLL = 23, RX DLL = 48, 20-25 pF loading per GPIO, and slew rate for all GPIO set to 6, DRIVESTRENGTH = STRONG.

Table 4.54. QSPI SDR Mode Timing (Location 0)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Full SCLK period	T		$(1/F_{SCLK}) * 0.95$	—	—	ns
Output valid	tov		—	—	T/2 - 2.4	ns
Output hold	toH		T/2 - 32.9	—	—	ns
Input setup	tsu		36.2 - T/2	—	—	ns
Input hold	tH		T/2 - 3.3	—	—	ns

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PB2	M2	GPIO	PB3	M3	GPIO
PC6	M14	GPIO	VREGVSS	M15 N16	Voltage regulator VSS
VREGSW	M16	DCDC regulator switching node	PB4	N1	GPIO
PB5	N2	GPIO	PB6	N3	GPIO
PD5	N14	GPIO	PD4	N15	GPIO
PC0	P1	GPIO (5V)	PC1	P2	GPIO (5V)
PC2	P3	GPIO (5V)	PA8	P4	GPIO
PA11	P5	GPIO	PA13	P6	GPIO (5V)
PB9	P7	GPIO (5V)	PB12	P8	GPIO
PH2	P9	GPIO (5V)	PH5	P10	GPIO
PH8	P11	GPIO (5V)	PH11	P12	GPIO (5V)
PH13	P13	GPIO (5V)	PD0	P14	GPIO (5V)
PD3	P15	GPIO	PD8	P16	GPIO
PB7	R1	GPIO	PC3	R2	GPIO (5V)
PC5	R3	GPIO	PA9	R4	GPIO
BODEN	R5	Brown-Out Detector Enable. This pin may be left disconnected or tied to AVDD.	RESETn	R6	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.
PB10	R7	GPIO (5V)	PH0	R8	GPIO (5V)
PH3	R9	GPIO (5V)	PH6	R10	GPIO
PH9	R11	GPIO (5V)	PH12	R12	GPIO (5V)
PH14	R13	GPIO (5V)	PH15	R14	GPIO (5V)
PD2	R15	GPIO (5V)	PD7	R16	GPIO
PB8	T1	GPIO	PC4	T2	GPIO
PA7	T3	GPIO	PA10	T4	GPIO
PA12	T5	GPIO (5V)	PA14	T6	GPIO
PB11	T7	GPIO	PH1	T8	GPIO (5V)
PH4	T9	GPIO	PH7	T10	GPIO (5V)
PH10	T11	GPIO (5V)	PB13	T12	GPIO
PB14	T13	GPIO	AVDD	T14	Analog power supply.
PD1	T15	GPIO	PD6	T16	GPIO

Note:

1. GPIO with 5V tolerance are indicated by (5V).
2. The pins PD13, PD14, and PD15 will not be 5V tolerant on all future devices. In order to preserve upgrade options with full hardware compatibility, do not use these pins with 5V domains.

5.12 EFM32GG11B8xx in QFP64 Device Pinout

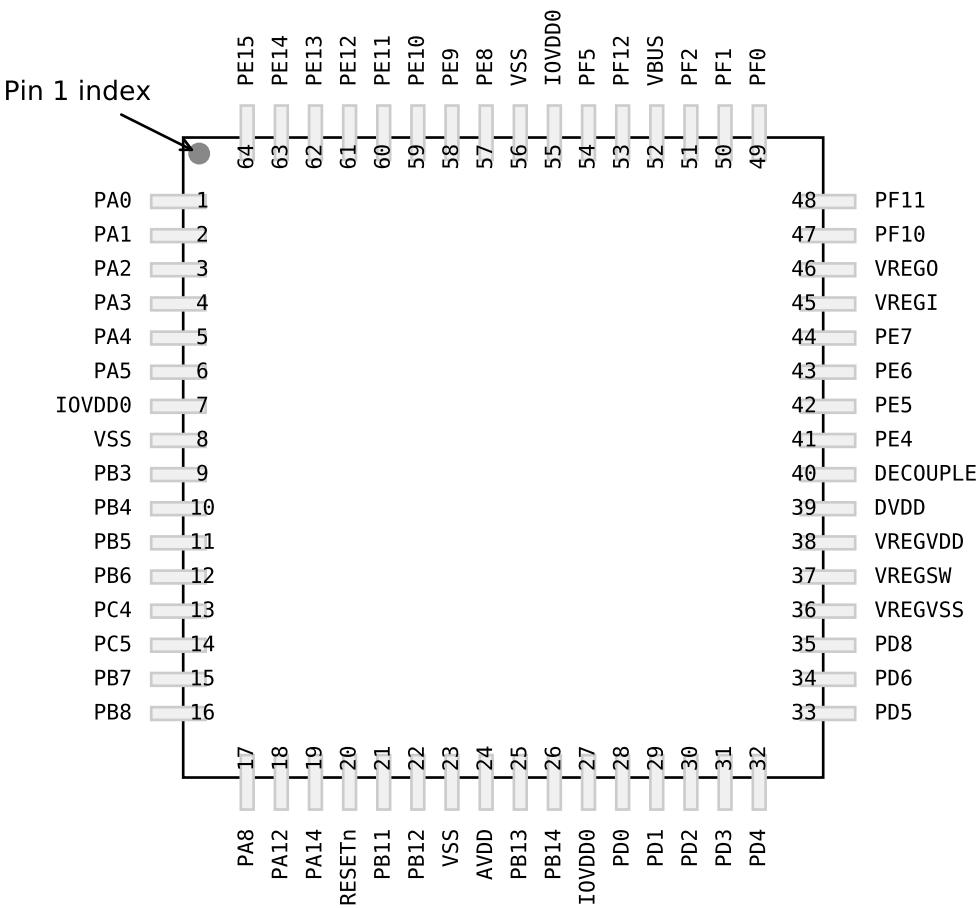


Figure 5.12. EFM32GG11B8xx in QFP64 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.20 GPIO Functionality Table](#) or [5.21 Alternate Functionality Overview](#).

Table 5.12. EFM32GG11B8xx in QFP64 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	PA3	4	GPIO
PA4	5	GPIO	PA5	6	GPIO
IOVDD0	7 27 55	Digital IO power supply 0.	VSS	8 23 56	Ground
PB3	9	GPIO	PB4	10	GPIO
PB5	11	GPIO	PB6	12	GPIO

5.15 EFM32GG11B1xx in QFP64 Device Pinout

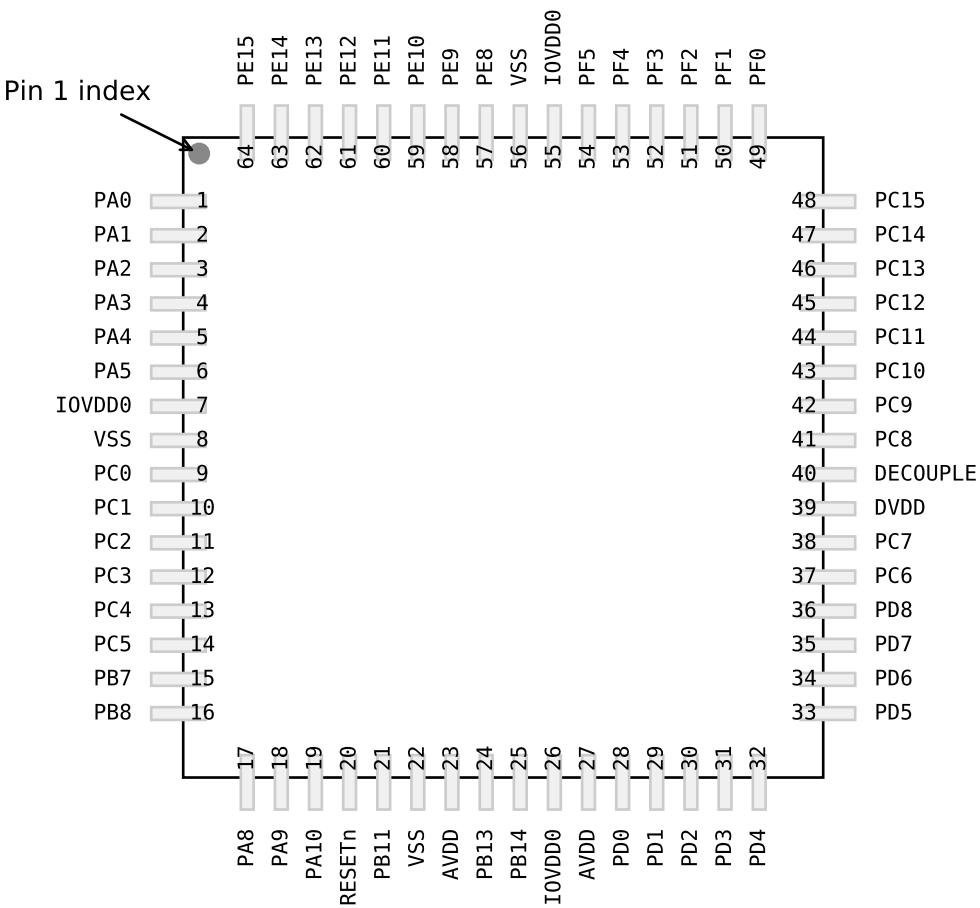


Figure 5.15. EFM32GG11B1xx in QFP64 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.20 GPIO Functionality Table](#) or [5.21 Alternate Functionality Overview](#).

Table 5.15. EFM32GG11B1xx in QFP64 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	PA3	4	GPIO
PA4	5	GPIO	PA5	6	GPIO
IOVDD0	7 26 55	Digital IO power supply 0.	VSS	8 22 56	Ground
PC0	9	GPIO (5V)	PC1	10	GPIO (5V)
PC2	11	GPIO (5V)	PC3	12	GPIO (5V)

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PC4	13	GPIO	PC5	14	GPIO
PB7	15	GPIO	PB8	16	GPIO
PA8	17	GPIO	PA9	18	GPIO
PA10	19	GPIO	RESETn	20	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.
PB11	21	GPIO	AVDD	23 27	Analog power supply.
PB13	24	GPIO	PB14	25	GPIO
PD0	28	GPIO (5V)	PD1	29	GPIO
PD2	30	GPIO (5V)	PD3	31	GPIO
PD4	32	GPIO	PD5	33	GPIO
PD6	34	GPIO	PD7	35	GPIO
PD8	36	GPIO	PC6	37	GPIO
PC7	38	GPIO	DVDD	39	Digital power supply.
DECUPLE	40	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.	PC8	41	GPIO (5V)
PC9	42	GPIO (5V)	PC10	43	GPIO (5V)
PC11	44	GPIO (5V)	PC12	45	GPIO (5V)
PC13	46	GPIO (5V)	PC14	47	GPIO (5V)
PC15	48	GPIO (5V)	PF0	49	GPIO (5V)
PF1	50	GPIO (5V)	PF2	51	GPIO
PF3	52	GPIO	PF4	53	GPIO
PF5	54	GPIO	PE8	57	GPIO
PE9	58	GPIO	PE10	59	GPIO
PE11	60	GPIO	PE12	61	GPIO
PE13	62	GPIO	PE14	63	GPIO
PE15	64	GPIO			

Note:

1. GPIO with 5V tolerance are indicated by (5V).

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PB6	12	GPIO	PC4	13	GPIO
PC5	14	GPIO	PB7	15	GPIO
PB8	16	GPIO	PA8	17	GPIO
PA12	18	GPIO (5V)	PA13	19	GPIO (5V)
PA14	20	GPIO	RESETn	21	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.
PB11	22	GPIO	PB12	23	GPIO
AVDD	24	Analog power supply.	PB13	25	GPIO
PB14	26	GPIO	PD0	28	GPIO (5V)
PD1	29	GPIO	PD2	30	GPIO (5V)
PD3	31	GPIO	PD4	32	GPIO
PD5	33	GPIO	PD6	34	GPIO
PD8	35	GPIO	VREGVSS	36	Voltage regulator VSS
VREGSW	37	DCDC regulator switching node	VREGVDD	38	Voltage regulator VDD input
DVDD	39	Digital power supply.	DECOPPLE	40	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.
PE4	41	GPIO	PE5	42	GPIO
PE6	43	GPIO	PE7	44	GPIO
VREGI	45	Input to 5 V regulator.	VREGO	46	Decoupling for 5 V regulator and regulator output. Power for USB PHY in USB-enabled OPNs
PF10	47	GPIO (5V)	PF11	48	GPIO (5V)
PF0	49	GPIO (5V)	PF1	50	GPIO (5V)
PF2	51	GPIO	VBUS	52	USB VBUS signal and auxiliary input to 5 V regulator.
PF12	53	GPIO	PF5	54	GPIO
PE8	56	GPIO	PE9	57	GPIO
PE10	58	GPIO	PE11	59	GPIO
PE12	60	GPIO	PE13	61	GPIO
PE14	62	GPIO	PE15	63	GPIO
PA15	64	GPIO			

Note:

1. GPIO with 5V tolerance are indicated by (5V).

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
ETH_MDIO	0: PB3 1: PD13 2: PC0 3: PA15		Ethernet Management Data I/O.
ETH_MIICOL	0: PB2 1: PG15 2: PB4		Ethernet MII Collision Detect.
ETH_MIICRS	0: PB1 1: PG14 2: PB3		Ethernet MII Carrier Sense.
ETH_MIIRXCLK	0: PA15 1: PG7 2: PD12		Ethernet MII Receive Clock.
ETH_MIIRXD0	0: PE12 1: PG11 2: PF9		Ethernet MII Receive Data Bit 0.
ETH_MIIRXD1	0: PE13 1: PG10 2: PD9		Ethernet MII Receive Data Bit 1.
ETH_MIIRXD2	0: PE14 1: PG9 2: PD10		Ethernet MII Receive Data Bit 2.
ETH_MIIRXD3	0: PE15 1: PG8 2: PD11		Ethernet MII Receive Data Bit 3.
ETH_MIIRXDV	0: PE11 1: PG12 2: PF8		Ethernet MII Receive Data Valid.
ETH_MIIRXER	0: PE10 1: PG13 2: PF7		Ethernet MII Receive Error.
ETH_MIITXCLK	0: PA0 1: PG0		Ethernet MII Transmit Clock.
ETH_MIITXD0	0: PA4 1: PG4		Ethernet MII Transmit Data Bit 0.
ETH_MIITXD1	0: PA3 1: PG3		Ethernet MII Transmit Data Bit 1.

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
ETH_MIITXD2	0: PA2 1: PG2		Ethernet MII Transmit Data Bit 2.
ETH_MIITXD3	0: PA1 1: PG1		Ethernet MII Transmit Data Bit 3.
ETH_MIITXEN	0: PA5 1: PG5		Ethernet MII Transmit Enable.
ETH_MIITXER	0: PA6 1: PG6		Ethernet MII Transmit Error.
ETH_RMIICRSDV	0: PA4 1: PD11		Ethernet RMII Carrier Sense / Data Valid.
ETH_RMIIREFCLK	0: PA3 1: PD10		Ethernet RMII Reference Clock.
ETH_RMIIRXD0	0: PA2 1: PD9		Ethernet RMII Receive Data Bit 0.
ETH_RMIIRXD1	0: PA1 1: PF9		Ethernet RMII Receive Data Bit 1.
ETH_RMIIRXER	0: PA5 1: PD12		Ethernet RMII Receive Error.
ETH_RMIITXD0	0: PE15 1: PF7		Ethernet RMII Transmit Data Bit 0.
ETH_RMIITXD1	0: PE14 1: PF6		Ethernet RMII Transmit Data Bit 1.
ETH_RMIITXEN	0: PA0 1: PF8		Ethernet RMII Transmit Enable.
ETH_TSUEXTCLK	0: PB5 1: PD15 2: PC2 3: PF8		Ethernet IEEE1588 External Reference Clock.

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
ETH_TSUTMR-TOG	0: PB6 1: PB15 2: PC3 3: PF9		Ethernet IEEE1588 Timer Toggle.
ETM_TCLK	0: PD7 1: PF8 2: PC6 3: PA6	4: PE11 5: PG15	Embedded Trace Module ETM clock .
ETM_TD0	0: PD6 1: PF9 2: PC7 3: PA2	4: PE12 5: PG14	Embedded Trace Module ETM data 0.
ETM_TD1	0: PD3 1: PD13 2: PD3 3: PA3	4: PE13 5: PG13	Embedded Trace Module ETM data 1.
ETM_TD2	0: PD4 1: PB15 2: PD4 3: PA4	4: PE14 5: PG12	Embedded Trace Module ETM data 2.
ETM_TD3	0: PD5 1: PF3 2: PD5 3: PA5	4: PE15 5: PG11	Embedded Trace Module ETM data 3.
GPIO_EM4WU0	0: PA0		Pin can be used to wake the system up from EM4
GPIO_EM4WU1	0: PA6		Pin can be used to wake the system up from EM4
GPIO_EM4WU2	0: PC9		Pin can be used to wake the system up from EM4
GPIO_EM4WU3	0: PF1		Pin can be used to wake the system up from EM4
GPIO_EM4WU4	0: PF2		Pin can be used to wake the system up from EM4
GPIO_EM4WU5	0: PE13		Pin can be used to wake the system up from EM4
GPIO_EM4WU6	0: PC4		Pin can be used to wake the system up from EM4

7.3 BGA152 Package Marking



Figure 7.3. BGA152 Package Marking

The package marking consists of:

- PPPPPPPPPP – The part number designation.
- TTTTTT – A trace or manufacturing code. The first letter is the device revision.
- YY – The last 2 digits of the assembly year.
- WW – The 2-digit workweek when the device was assembled.

13. Revision History

Revision 0.6

March, 2018

- Removed "Confidential" watermark.
- Updated [4.1 Electrical Characteristics](#) and [4.2 Typical Performance Curves](#) with latest characterization data.

Revision 0.2

October, 2017

- Updated memory maps to latest formatting and to include all peripherals.
- Updated all electrical specifications tables with latest characterization results.
- **Absolute Maximum Ratings Table:**
 - Removed redundant I_{VSSMAX} line.
 - Added footnote to clarify V_{DIGPIN} specification for 5V tolerant GPIO.
- **General Operating Conditions Table:**
 - Removed dV_{DD} specification and redundant footnote about shorting VREGVDD and AVDD together.
 - Added footnote about IOVDD voltage restriction when CSEN peripheral is used with chopping enabled.
- **Flash Memory Characteristics Table:** Added timing measurement clarification for Device Erase and Mass Erase.
- **Analog to Digital Converter (ADC) Table:**
 - Added header text for general specification conditions.
 - Added footnote for clarification of input voltage limits.
- Minor typographical corrections, including capitalization, mis-spellings and punctuation marks, throughout document.
- Minor formatting and styling updates, including table formats, TOC location, and boilerplate information throughout document.

Revision 0.1

April 27th, 2017

Initial release.



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